



# UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER OF PATENTS AND TRADEMARKS Washington, D.C. 20231 www.uspto.gov

APPLICATION NO.	· FI	LING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/853,111	09/853,111 05/10/2001		Salman Akram	MICT-0012-D1-US (97-0141)	7172
21906	7590	04/03/2002			
TROP PRU	MER & I	·IU, PC	EXAMINER		
8554 KATY SUITE 100		CHAMBLISS, ALONZO			
HOUSTON, TX 77024			ART UNIT	PAPER NUMBER	
				2827	
				DATE MAILED: 04/03/2002	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)
	•	09/853,111	AKRAM, SALMAN
١.	Office Action Summary	Examiner	Art Unit
		Alonzo Chambliss	2827
Dania	The MAILING DATE of this communication a	appears on the cover sheet w	ith the correspondence address
A : TH - ! - !	SHORTENED STATUTORY PERIOD FOR REF HE MAILING DATE OF THIS COMMUNICATION Extensions of time may be available under the provisions of 37 CFR after SIX (6) MONTHS from the mailing date of this communication. If the period for reply specified above is less than thirty (30) days, a I If NO period for reply is specified above, the maximum statutory periform Failure to reply within the set or extended period for reply will, by sta Any reply received by the Office later than three months after the may parmed patent term adjustment. See 37 CFR 1.704(b).	N. 1.136(a). In no event, however, may a literal within the statutory minimum of thir tod will apply and will expire SIX (6) MON that a cause the application to become Al	reply be timely filed ty (30) days will be considered timely. ITHS from the mailing date of this communication. BANDONED (35 U.S.C. § 133).
	Responsive to communication(s) filed on 1	9 February 2002 .	
2a)		This action is non-final.	
,	<ul> <li>Since this application is in condition for alloclosed in accordance with the practice unconsition of Claims</li> </ul>	owance except for formal ma ler <i>Ex parte Quayle</i> , 1935 C.	atters, prosecution as to the merits is D. 11, 453 O.G. 213.
•	⊠ Claim(s) 15-22 and 32-35 is/are pending in	the application.	
ŕ	4a) Of the above claim(s) is/are without		
5)	Claim(s) is/are allowed.		
6)	☑ Claim(s) <u>15-22 and 32-35</u> is/are rejected.		
7)	Claim(s) is/are objected to.		
	Claim(s) are subject to restriction an	d/or election requirement.	
• •	cation Papers		
	☐ The specification is objected to by the Exam		Ah a Everyiner
10)	☐ The drawing(s) filed on is/are: a)☐ a		
	Applicant may not request that any objection t  The proposed drawing correction filed on		
11)	The proposed drawing correction filed on If approved, corrected drawings are required in		disapproved by the Examinor.
40	if approved, corrected drawings are required in the oath or declaration is objected to by the		
	ity under 35 U.S.C. §§ 119 and 120		
1	) Acknowledgment is made of a claim for for	eian priority under 35 U.S.C	. § 119(a)-(d) or (f).
13	a) All b) Some * c) None of:		
	1. Certified copies of the priority docum	nents have been received.	
	2. ☐ Certified copies of the priority docum		Application No
	3. Copies of the certified copies of the application from the Internationa	priority documents have bee Il Bureau (PCT Rule 17.2(a))	n received in this National Stage
	* See the attached detailed Office action for a  Acknowledgment is made of a claim for dom		
14)	a) ☐ The translation of the foreign language		
1	) ☐ Acknowledgment is made of a claim for dor	nestic priority under 35 U.S.	C. §§ 120 and/or 121.
1	hment(s)	4) 🗍 Intervie	w Summary (PTO-413) Paper No(s)
2) 🔲	Notice of References Cited (PTO-892)  Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO-1449) Pager No.	3) 5) Notice	of Informal Patent Application (PTO-152)

Art Unit: 2827

#### **DETAILED ACTION**

1. The amendment B filed 2/19/02 has been fully considered and made of record as Paper No. 3.

## Response to Arguments

2. Applicant's arguments with respect to claims 15-22 and 32-35 have been considered but are moot in view of the new ground(s) of rejection. This action is made **Non-final**.

### Specification

3. The abstract of the disclosure is objected to because one of the essential elements in the applicant's invention (i.e. spacer) is not defined in the abstract.

Correction is required. See MPEP § 608.01(b).

## Claim Rejections - 35 USC § 102

- 4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:
  - (e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) do not apply to the examination of this application as the application being examined

Art Unit: 2827

was not (1) filed on or after November 29, 2000, or (2) voluntarily published under 35 U.S.C. 122(b). Therefore, this application is examined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).

5. Claims15-22 and 32-35 are rejected under 35 U.S.C. 102(b) as being anticipated by Alagaratnam et al. (U.S. 5,814,881).

With respect to Claims 15, 21, 32, and 33, Waki teaches stacking at least two semiconductor dies 14, 40 having substantially the same rectangular dimensions on top of one another. The dies 14, 40 are electrically connected to the lead frame. Bonding pads 34, 35, 46, and 47 of the dies 14, 40 are wire bonded to the lead fingers 61 of the lead frame (see col. 4 lines 1-5; Fig. 1). The first die 14 is mounted on the lead frame by the die paddle 12. The second die 40 is mounted only on the first die 14 (see Fig. 1).

With respect to Claims 16 and 34, the first and second dies 14, 40 are mounted in a back-to-back configuration (see Fig. 1).

With respect to Claims 17 and 35, the first die 14 is adhered to the second die 40 by an adhesive layer (see Fig. 1).

With respect to Claim 18, the first die 14 has a lead (i.e. wire) on chip configuration (see Fig. 1).

With respect to Claim 19, first die 14 is secured to the lead frame and the second die 40 is secured to the lead frame by the first die 14 (see Fig. 1).

With respect to Claim 20, the semiconductor dies 14, 40 are wire bonded to the lead frame, wherein the dies 14, 40 have facing sides and outwardly facing sides by extending wire to bond pads 34, 35, 46, and 47 on the outwardly facing sides of the dies

Application/Control Number: 09/853,111

Art Unit: 2827

(see Fig. 1). The outwardly facing sides are the sides of the die that have bonding pads 34, 35, 46, and 47 on the surfaces.

With respect to Claim 22, the semiconductor dies 14, 40 and the lead frame are encapsulated in a single package body 90 (see Fig. 1).

#### Conclusion

6. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. It is cited primarily to show processes of packaging a semiconductor device, which are similar to the process of the instant invention.

Any inquiry concerning the communication or earlier communications from the examiner should be directed to Alonzo Chambliss whose telephone number is (703) 306-9143. The fax phone number for this Group is (703) 308-7722 or 7724.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the Group receptionist whose telephone number is (703) 308-7956.

DAVID L. TALBOTT PRIMARY EXAMINER

ART UNIT 258

2827

AC

AC/March 27, 2002